

Material Profile: Superior™ F815

Superior F815 was specifically developed to be a cost-effective, high-performance compound for semiconductor applications. Superior F815 offers outstanding plasma resistance and low particulation in a wide range of plasma environments.

Features and Benefits

- Outstanding plasma resistance
- Minimum particulation
- Wide chemical resistance
- High physical properties
- Cost-effective

Recommended Processes

- Deposition: CVD, APCVD, HDPCVD, PECVD. RPCVD. SACVD
- Plasma etch: poly, oxide and metal
- Ashing
- Metallization: PVD, sputtering
- Ion Implant



Specialty Fluoroelastomer with No Carbon Fillers Service Temperature Range: - 30 to 220°C

Equipment Locations

- Chamber Lid Seals
- Bell Jar Seals
- Endpoint Windows
- Gas Inlet Seals
- Isolator Valve Seals
- KF Fittings
- Slit Valve Seals
- Valve Seals
- Window Seals

Typical Physical Properties

Color Black
Shore A Durometer 75
Tensile Strength, psi (MPa) 3280 (22.6)
Elongation 420%
Modulus at 100% Elongation,
psi (MPa) 595 (4.1)
Compression Set: 70 hrs. at 200°C 29%

Service Temperature Range, °C (°F) -30 to 220 (-22 to 428)

The information contained herein is believed to be reliable, but no representation, guarantees or warranties of any kind are made to its accuracy or suitability for any purpose. The information presented herein is based on laboratory testing and does not necessarily indicate end product performance. Full scale testing and end product performance are the responsibility of the user.

